

<b>Notice of References Cited</b>	Application/Control No. 10/786,307	Applicant(s)/Patent Under Reexamination KIM ET AL.	
	Examiner Biju Chandran	Art Unit 2835	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,328,097 B1	12-2001	Bookhardt et al.	165/104.33
	B	US-			
	C	US-			
	D	US-			
	E	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	David A. Reay, Heat Pipe, in AccessScience@McGraw-Hill, <a href="http://www.accessscience.com">http://www.accessscience.com</a> , DOI 10.1036/1097-8542.757297, May 13, 2002
	V	Charles A. Harper, Cooling with Heat Pipes, Electronic packaging & Interconnection Handbook, Pages 2.79-2.80, Mc-Graw Hill, 1997
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.